



### **General Description**

The WSF45P10 is the highest performance trench P-Ch MOSFET with extreme high cell density , which provide excellent  $R_{\text{DSON}}$  and gate charge for most of the small power switching and load switch applications.

The WSF45P10 meet the RoHS and Green Product requirement with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

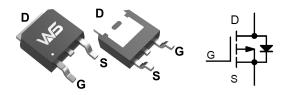
## **Product Summery**

BV <sub>DSS</sub>	R <sub>DSON</sub>	I <sub>D</sub>
-100V	44mΩ	-40A

## **Applications**

Inverters

## **TO-252 Pin Configuration**



## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Unit		
Common	Ratings (T <sub>C</sub> =25°C Unless Otherwise Noted)				
V <sub>DSS</sub>	Drain-Source Voltage		-100	_ <	
$V_{GSS}$	Gate-Source Voltage	±20			
T <sub>J</sub>	Maximum Junction Temperature	175	°C		
T <sub>STG</sub>	Storage Temperature Range	-55 to 175	°C		
I <sub>S</sub>	Diode Continuous Forward Current	T <sub>C</sub> =25°C	-40	А	
Mounted o	on Large Heat Sink				
I <sub>DM</sub>	Pulsed Drain Current *		-120**	А	
I <sub>D</sub>	Continuous Drain Current	T <sub>C</sub> =25°C	-40	A	
	Continuous Drain Current	T <sub>C</sub> =100°C	-26		
P <sub>D</sub>	Maximum Bayer Dissipation	T <sub>C</sub> =25°C	136	W	
	Maximum Power Dissipation	T <sub>C</sub> =100°C	68		
$R_{\theta JC}$	Thermal Resistance-Junction to Case		1.1	90/11	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	62.5	°C/W		
Avalanche	Ratings		•	•	
E <sub>AS</sub>	Avalanche Energy, Single Pulsed	L=0.5mH	308***	mJ	

Note: \* Repetitive rating; pulse width limited by junction temperatur

<sup>\*\*</sup> Drain current is limited by junction temperature

<sup>\*\*\*</sup> VD=-80V



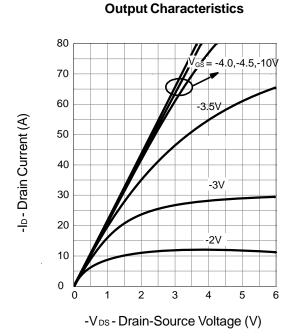
# Electrical Characteristics (T<sub>C</sub>=25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit				
Static Characteristics										
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =-250μA	-100	-	-	V				
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-100 V, V <sub>GS</sub> =0V	-	-	-1					
		T <sub>J</sub> =85°C	-	-	-10	μΑ				
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_{DS}=-250\mu A$	-1	-2	-3	V				
I <sub>GSS</sub>	Gate Leakage Current	$V_{GS}=\pm20V$ , $V_{DS}=0V$	-	-	±100	nA				
R <sub>DS(ON)</sub> *	Drain-Source On-state Resistance	V <sub>GS</sub> =-10V, I <sub>DS</sub> =-20A	-	44	55	mΩ				
R <sub>DS(ON)</sub> *	Drain-Source On-state Resistance	V <sub>GS</sub> =-4.5V, I <sub>DS</sub> =-20A	-	47	58.5	mΩ				
Diode Cha	aracteristics									
V <sub>SD</sub> *	Diode Forward Voltage	I <sub>SD</sub> =-20A, V <sub>GS</sub> =0V	-	-0.8	-1.2	V				
t <sub>rr</sub>	Reverse Recovery Time		-	70	-	ns				
Q <sub>rr</sub>	Reverse Recovery Charge	$I_{SD}$ =-20A, $dI_{SD}$ / $dt$ =-100A/ $\mu$ s	-	90	-	nC				
Dynamic (	Characteristics									
R <sub>G</sub>	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	-	2	-	Ω				
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =-20V, Frequency=1.0MHz	-	5720	-	pF				
C <sub>oss</sub>	Output Capacitance		-	790	-					
C <sub>rss</sub>	Reverse Transfer Capacitance		-	450	-					
t <sub>d(ON)</sub>	Turn-on Delay Time	$V_{DD}$ =-50V, $R_{G}$ = 6 $\Omega$ , $I_{DS}$ =-20A, $V_{GS}$ =-10V,	-	30	-	- ns				
T <sub>r</sub>	Turn-on Rise Time		-	79	-					
t <sub>d(OFF)</sub>	Turn-off Delay Time		-	82	-					
T <sub>f</sub>	Turn-off Fall Time		-	69	-					
Gate Chai	Gate Charge Characteristics									
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-80V,V <sub>GS</sub> =-10V, I <sub>DS</sub> =-20A	-	125	-	nC				
Q <sub>gs</sub>	Gate-Source Charge		-	21	-					
$Q_{gd}$	Gate-Drain Charge		-	45	-					

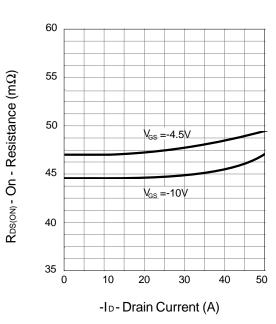
Note \* : Pulse test ; pulse width  $\leq$ 300 $\mu$ s, duty cycle  $\leq$ 2%.



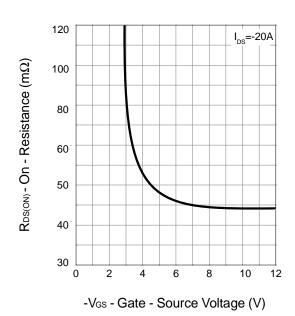
# **Typical Characteristics**



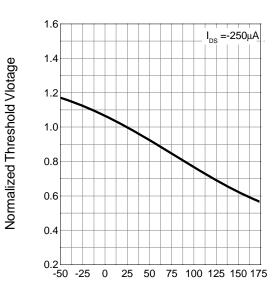
#### **Drain-Source On Resistance**



### **Drain-Source On Resistance**



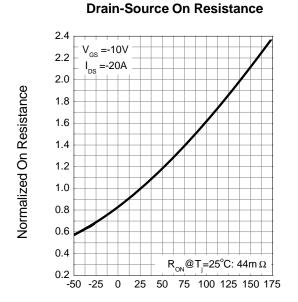
## **Gate Threshold Voltage**



T<sub>j</sub> - Junction Temperature (°C)

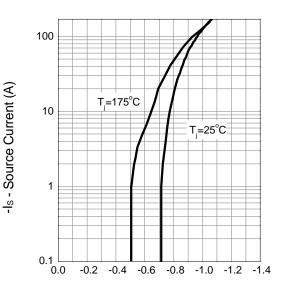


# **Typical Characteristics**



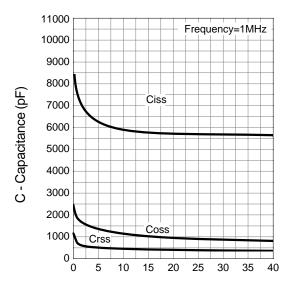
T<sub>j</sub>- Junction Temperature (°C)

#### **Source-Drain Diode Forward**



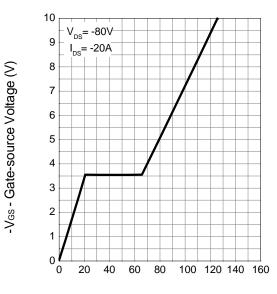
-Vsp - Source-Drain Voltage (V)

### Capacitance



-V<sub>DS</sub> - Drain - Source Voltage (V)

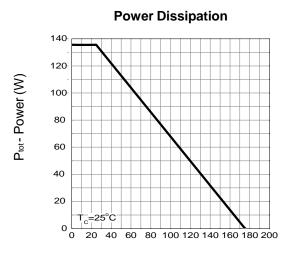
### **Gate Charge**



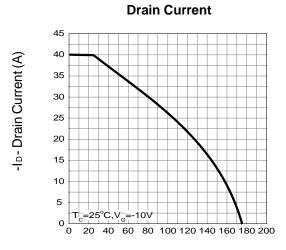
Q<sub>G</sub> - Gate Charge (nC)



# **Typical Characteristics**

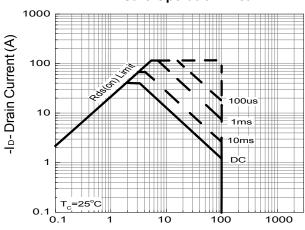


Tc- Case Temperature (°C)



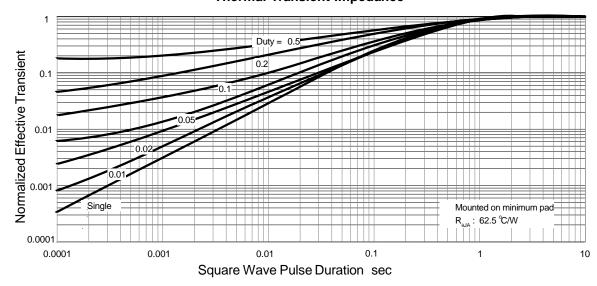
T<sub>c</sub>-Case Temperature (°C)

### **Safe Operation Area**



**Thermal Transient Impedance** 

-V<sub>DS</sub> - Drain - Source Voltage (V)





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